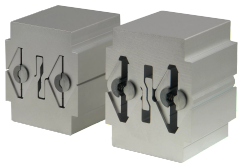


Interscale Flexible Heat Conductor (FHC), 70 mm

Power Utilities



Conductor block expands/contracts vertically to compensate for tolerance stack up and optimizes surface contact and pressure along the thermal path; eliminates the need for a thermal gap pad.

认证



功能

Designed for ATX/ITX/Mini ITX & COM using Intel core-iprocessors and AMD processors with the following sockets: Intel: LGA775, LGA1150, LGA1155, LGA1156, LGA1366, LGA2011 ; AMD: AM2, AM2(+), AM3, AM3(+), FM1, FM2, FM2(+)

Compatible with Interscale C enclosures

Provides industry leading conduction cooling performance, 70% improvement over current conduction cooling methods

Conductor block expands/contracts vertically to compensate for tolerance stack up and optimizes surface contact and pressure along the thermal path; eliminates the need for a thermal gap pad

Secured to PCB with mounting brackets, sold separately

技术参数

Table 1/1					
物料号	类型	搭配	包装数量	深度	宽度
24830-001	热导体	仪器箱	1	50 mm	50 mm

其他产品详情

Please order the mounting bracket (Intel or AMD, listed under accessories) to assemble the FHC to the board.

警告

应仅根据 nVent 的产品说明书与培训材料安装并使用 nVent 的产品。可访问 www.nvent.com 获取说明书，或者向您的 nVent 客服代表索取。错误安装、使用不当、滥用或未能完全遵守 nVent 的说明与警告，可能会造成产品故障、财产损失、严重的人身伤害及死亡和/或使得保修服务无效。



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